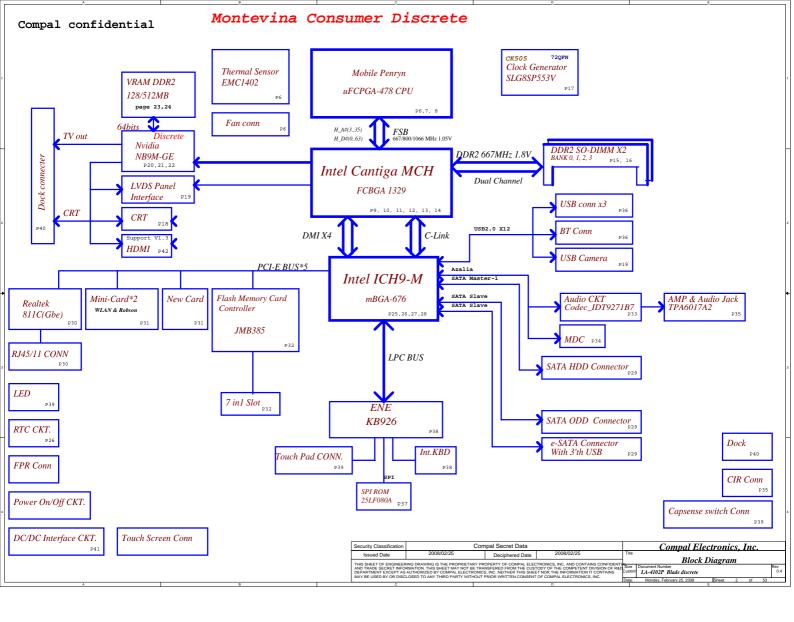
# Compal confidential

Schematics Document
Mobile Penryn uFCPGA with Intel
Cantiga\_PM+ICH9-M core logic

2008-02-25



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			Date:	Monday, February 25, 2008	Sheet	_1	of	53			



#### X MEANS OFF Voltage Rails O MEANS ON +5VS +3VS +1.5VS +0.9V power plane +B +5VALW +1.8V +VCCP +CPU\_CORE +2.5VS +1.8VS +NVVDD +3VALW State S0 o 0 0 o S1 0 o 0 o S3 0 0 0 X S5 S4/AC 0 X 0 X S5 S4/ Battery only X X X 0 S5 S4/AC & Battery don't exist X X X X

#### **SMBUS Control Table**

	SOURCE	INVERTER	BATT	SERIAL EEPROM	Thermal Sensor	SODIMM	CLK CHIP	MINI CARD	Sensor board	NB9M Thermal Sensor	NB9M	G-sensor
SMB_EC_CK1 SMB_EC_DA1	KB926	Х	V	V	Х	Х	Х	Х	V	Х	Х	Х
SMB_EC_CK2 SMB_EC_DA2	KB926	Х	Х	Х	٧	Х	Х	Х	Х	٧	V	Х
ICH_SMBCLK ICH_SMBDATA	ICH9	Х	X	Х	Х	V	V	V	Х	Х	Х	V

### **NB9M SMBUS Control Table**

	SOURCE	LVDS	CRT	номі
DDC2_DATA		V	Y	Y
DDC2_CLK	NB9M	•	_ ^	_ ^
3VDDCDA	NB9M	X	V	X
3VDDCCL	INDSIN	_ ^	•	_ ^
HDMIDAT_VGA	NB9M	Y	Y	V
HDMICLK_VGA	INEGIN	^	^	•

#### I2C / SMBUS ADDRESSING

DEVICE	HEX	ADDRESS
DDR SO-DIMM 0	A0	10100000
DDR SO-DIMM 1	A4	10100100
CLOCK GENERATOR (EXT.)	D2	11010010

#### Symbol Note:

: means Digital Ground

: means Analog Ground

 $@: means\ just\ reserve$  , no build DEBUG  $@: means\ just\ reserve$  for debug.

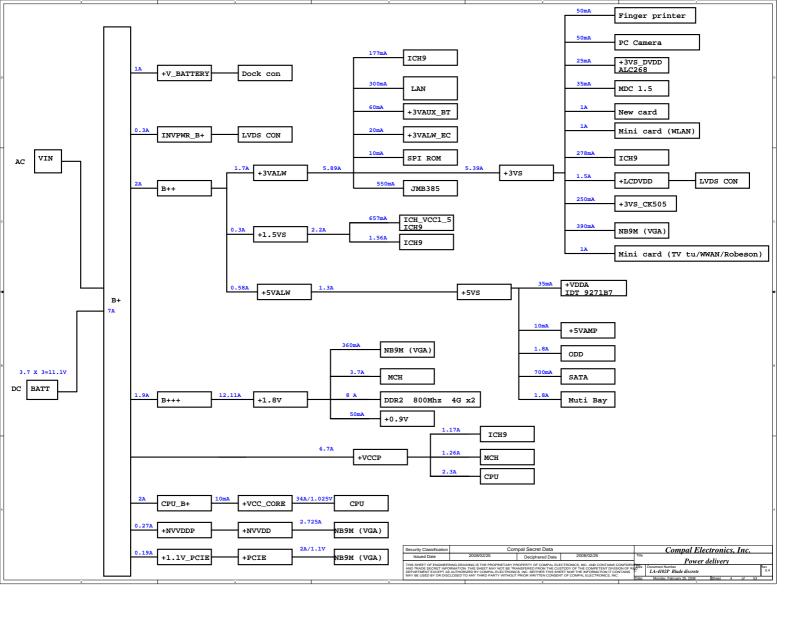
#### **USB** assignment:

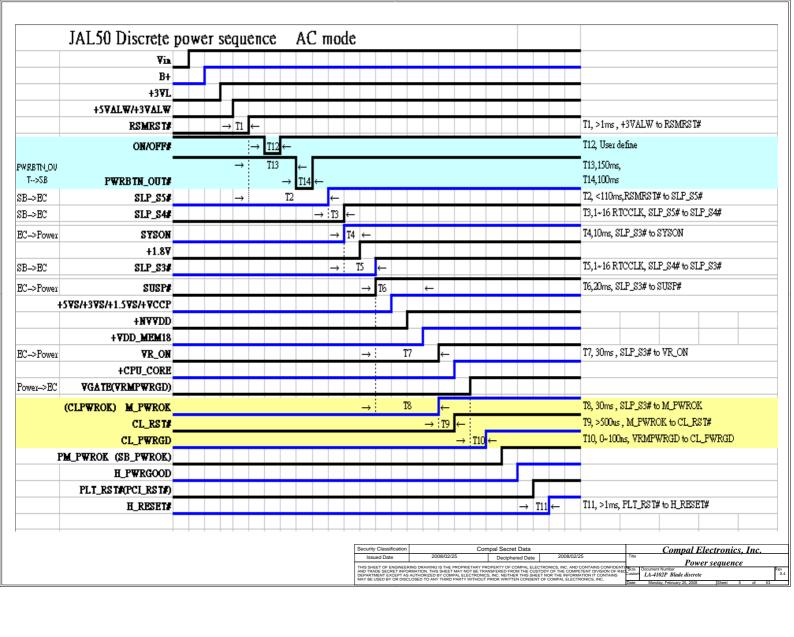
USB-0 Right side
USB-1 Right side
USB-1 Right side
USB-2 Left side(with ESATA)
USB-3 Dock
USB-4 Camera
USB-5 WLAN
USB-6 Bluetooth
USB-7 Finger Printer
USB-8 MiniCard(WWANTV)
USB-9 Express card
USB-10 X
USB-11 X

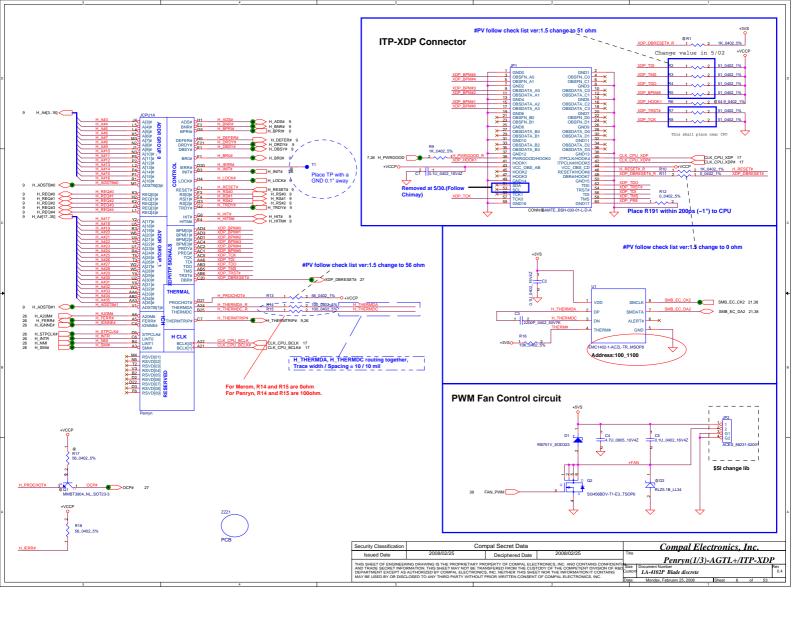
## PCIe assignment:

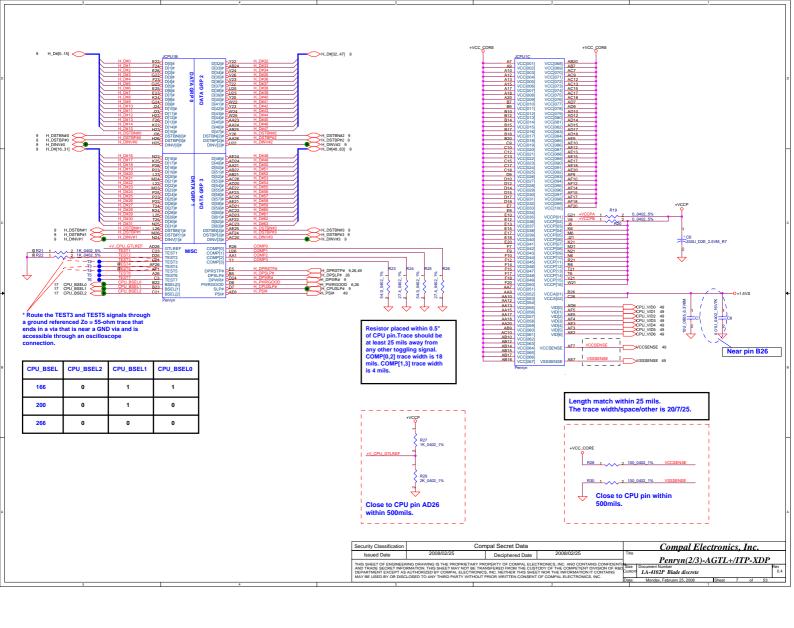
PCIe-1 TV tuner/WWAN/Robeson
PCIe-2 X
PCIe-3 WLAN
PCIe-4 GLAN (Marvell)
PCIe-5 Card reader
PCIe-6 New Card

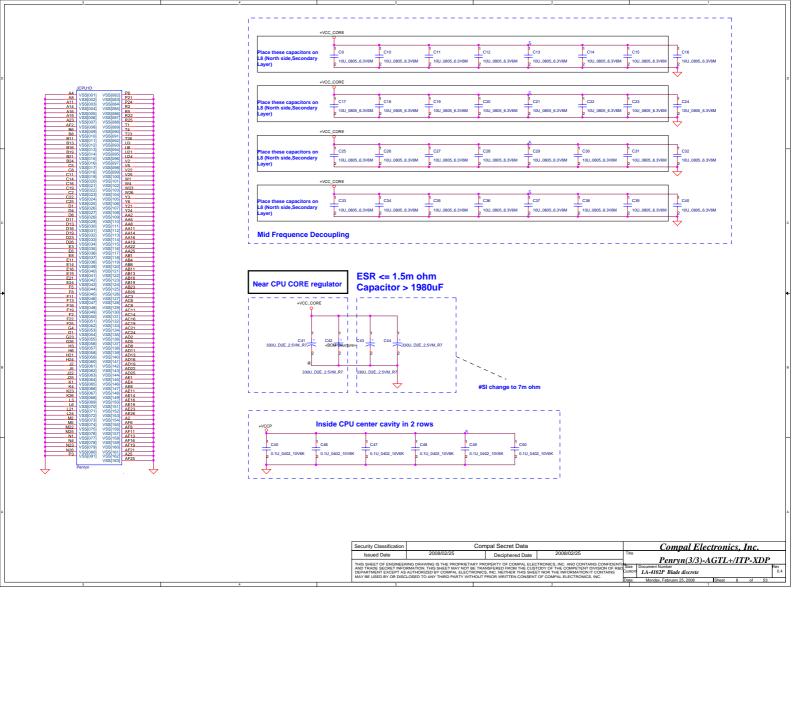
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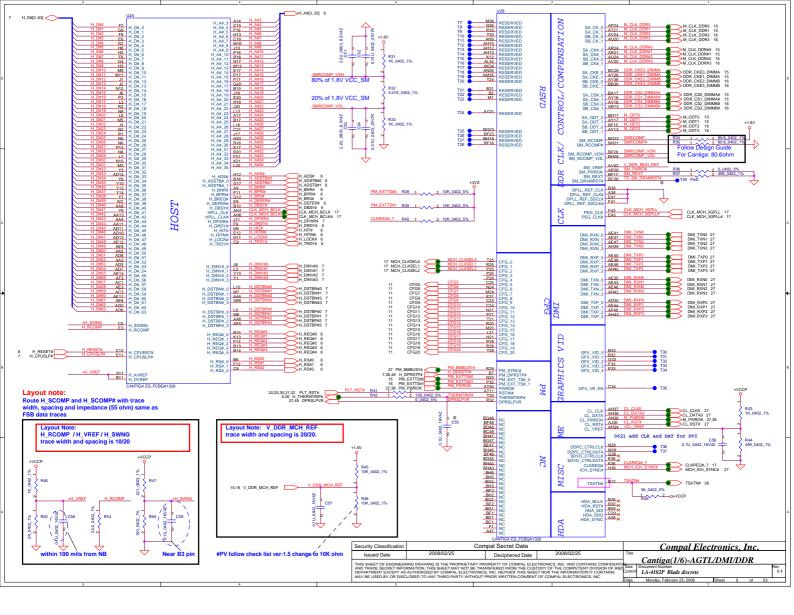


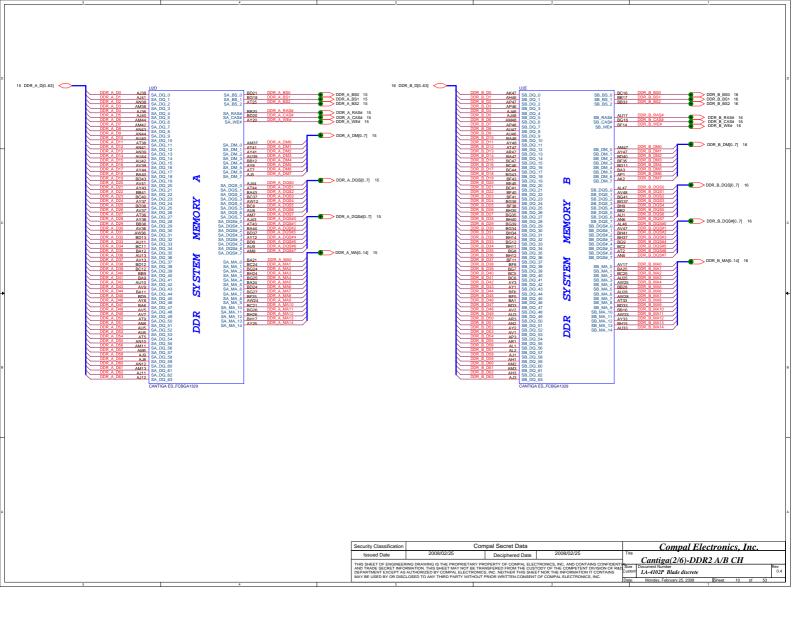


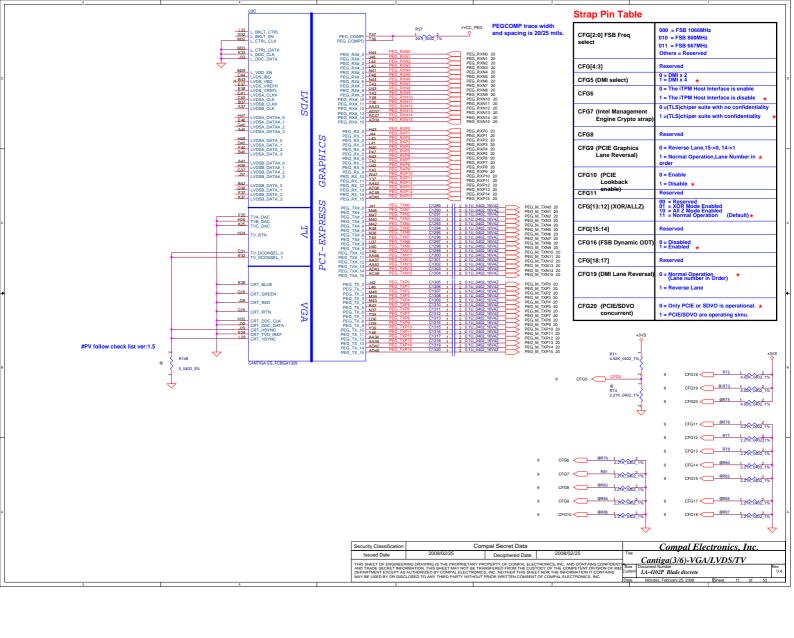


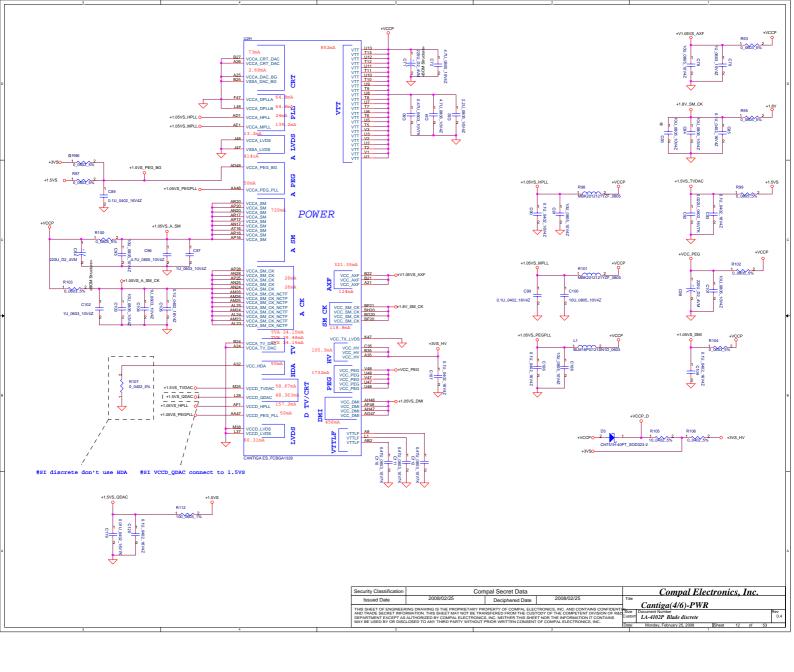


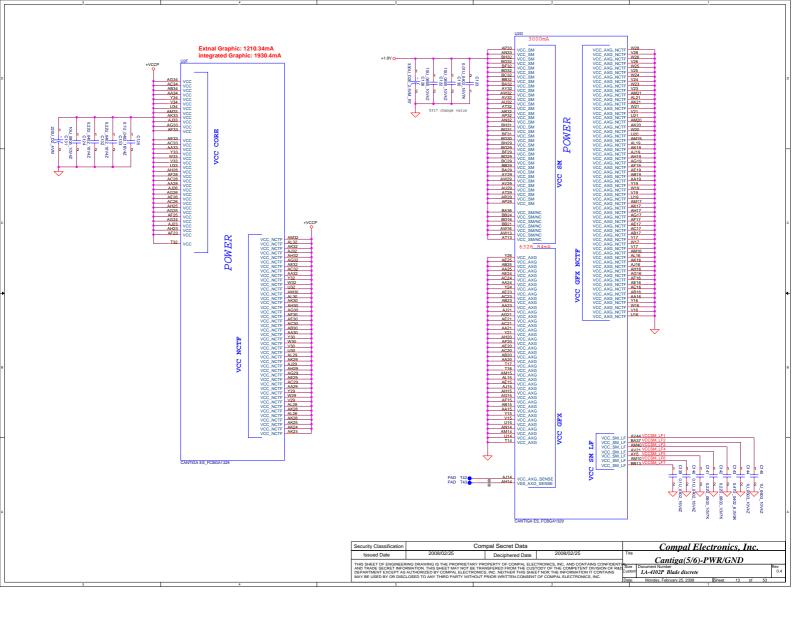


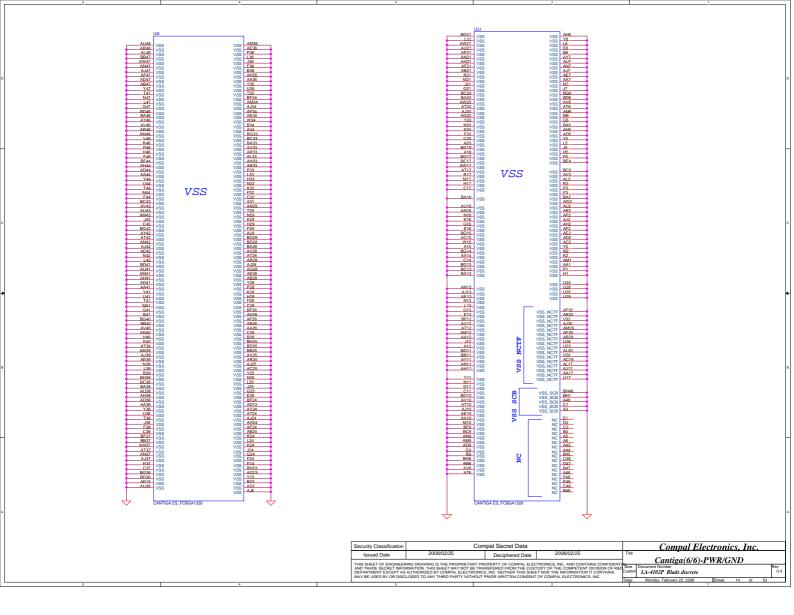


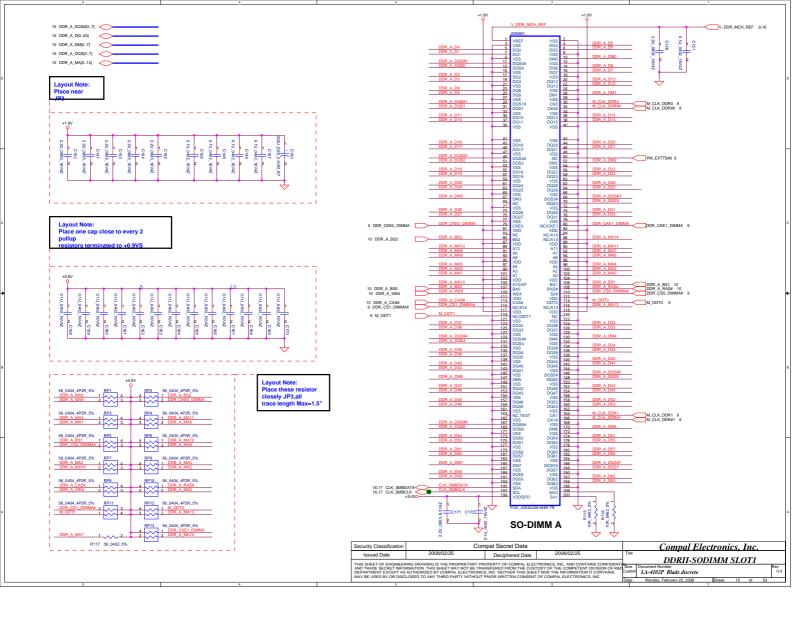


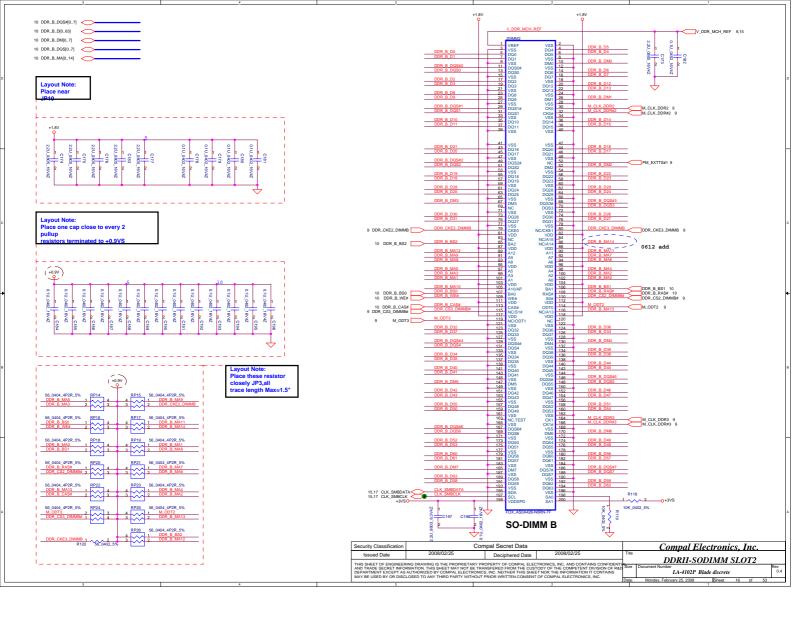


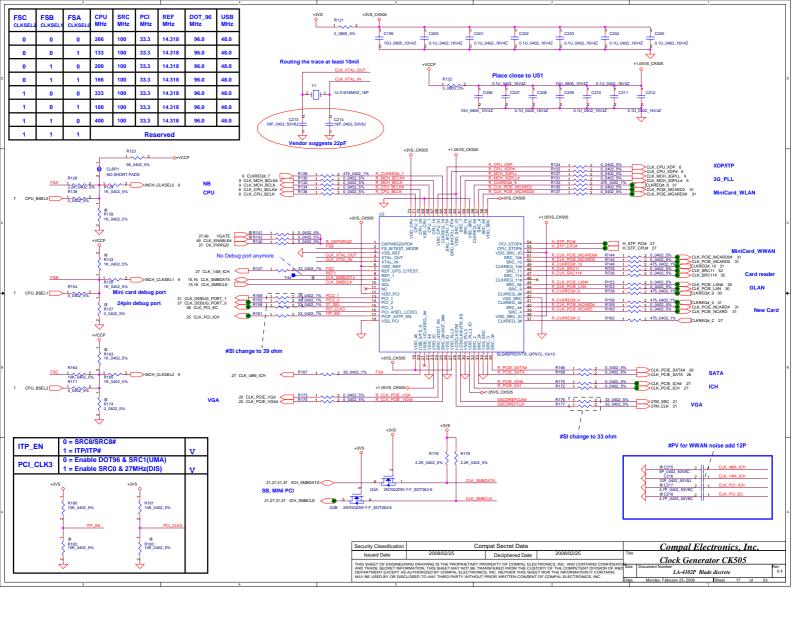


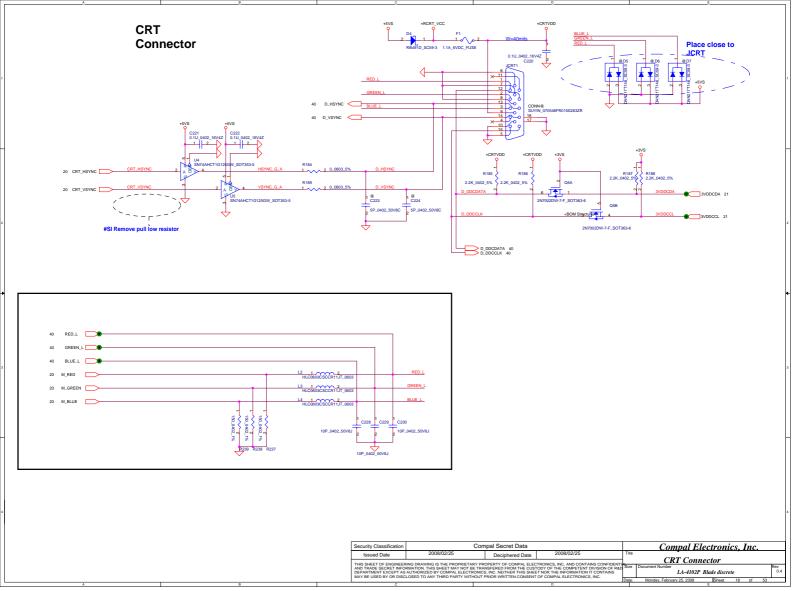


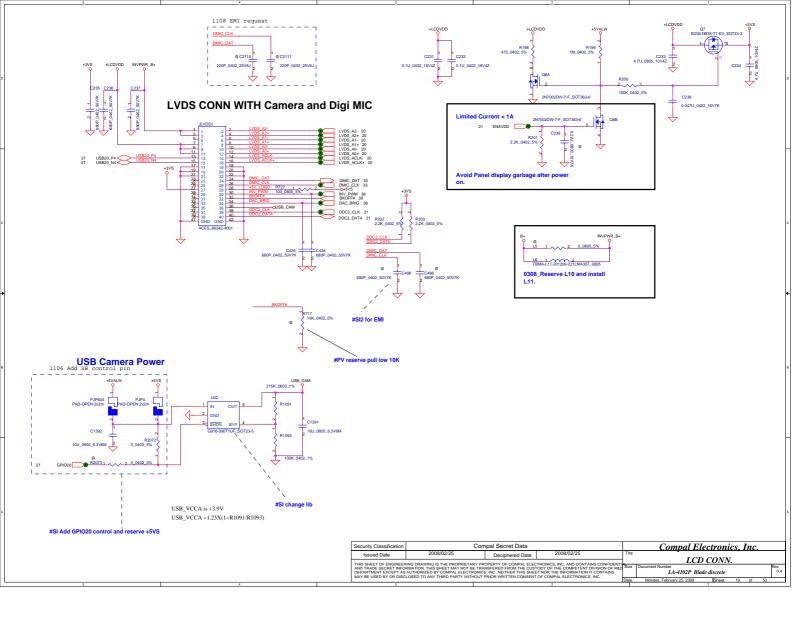


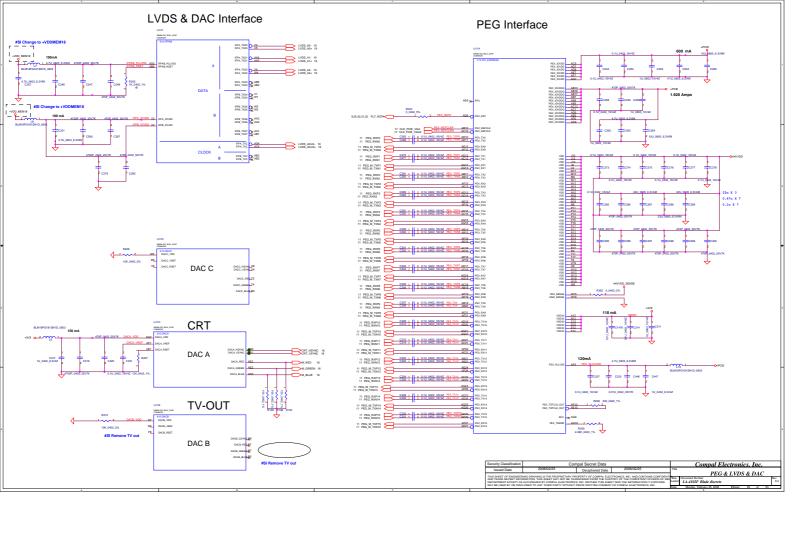


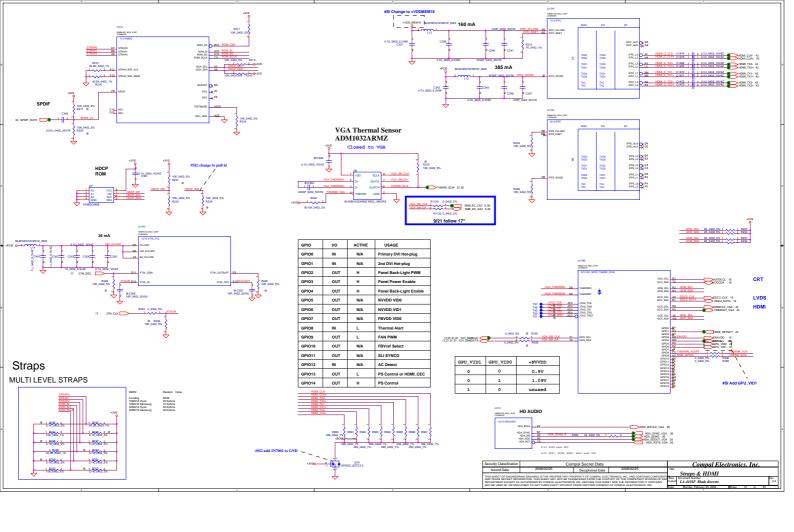


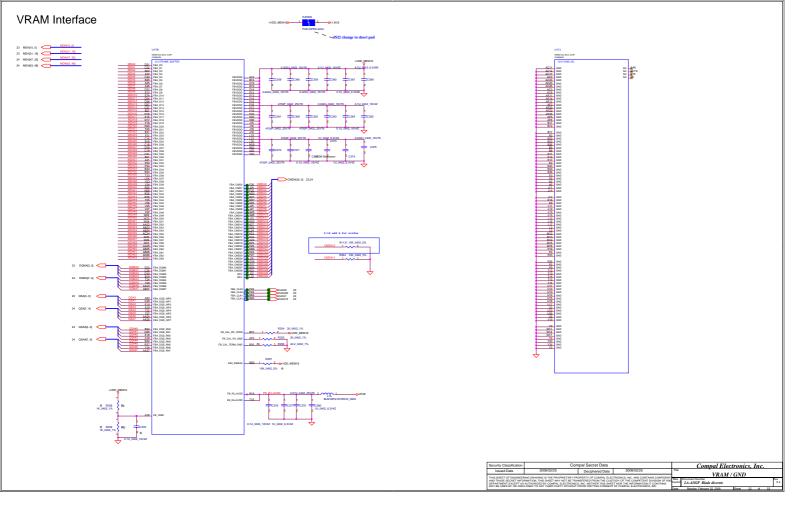


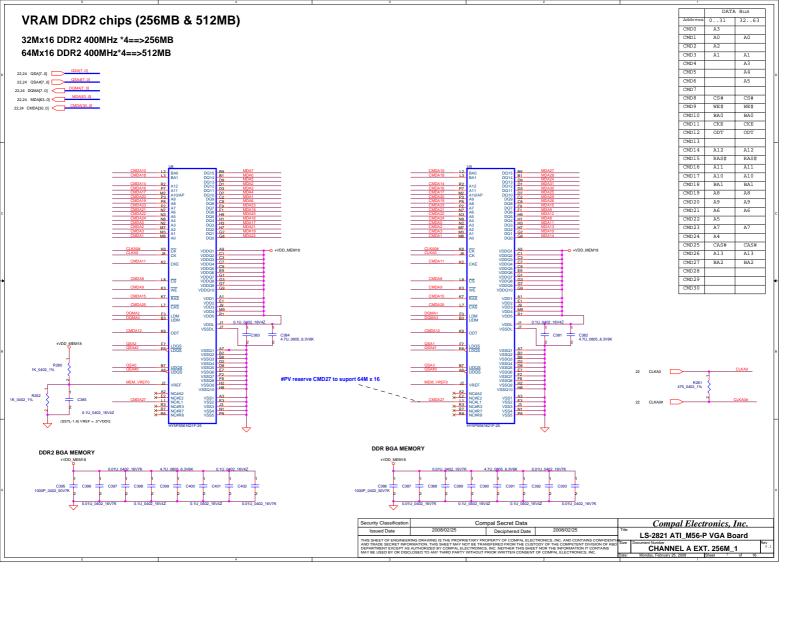


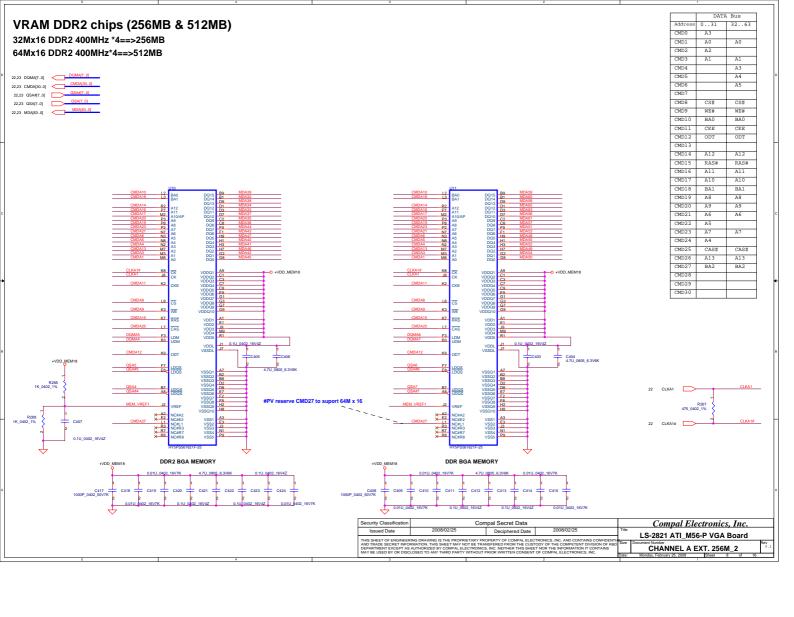


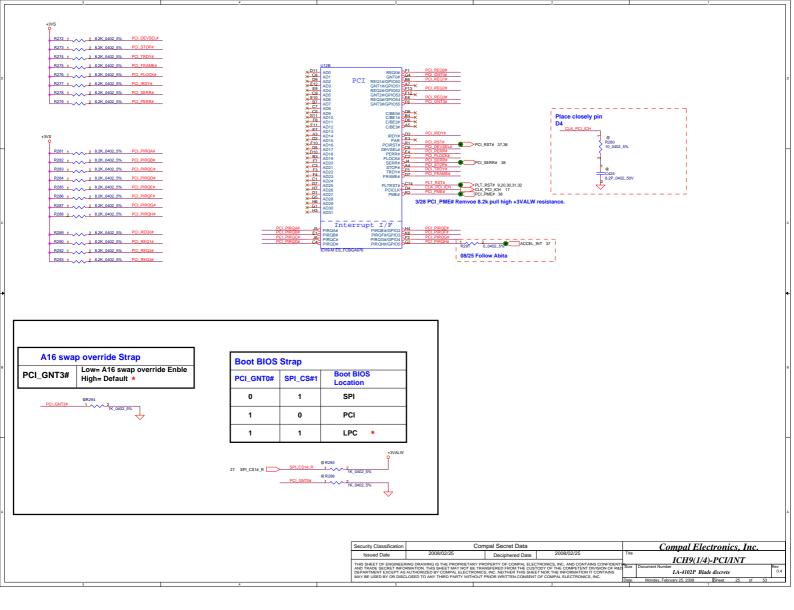






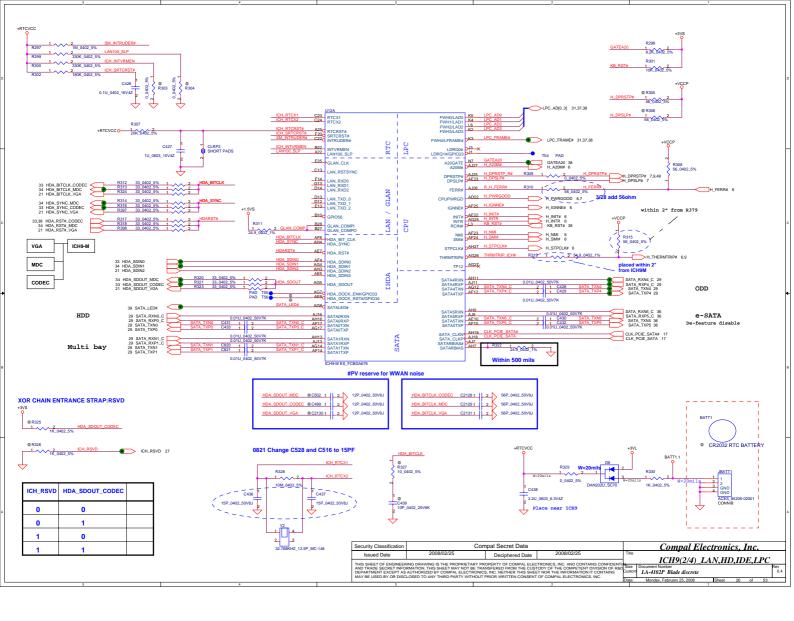


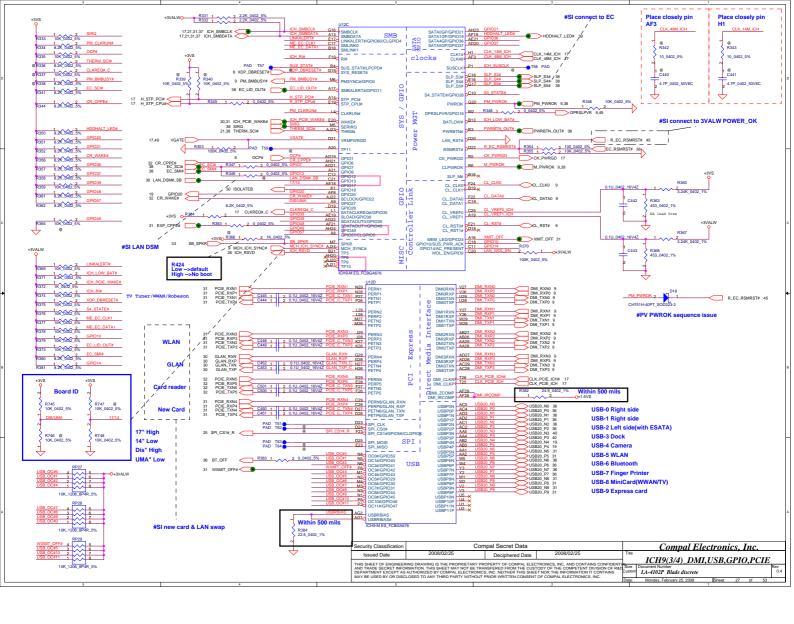


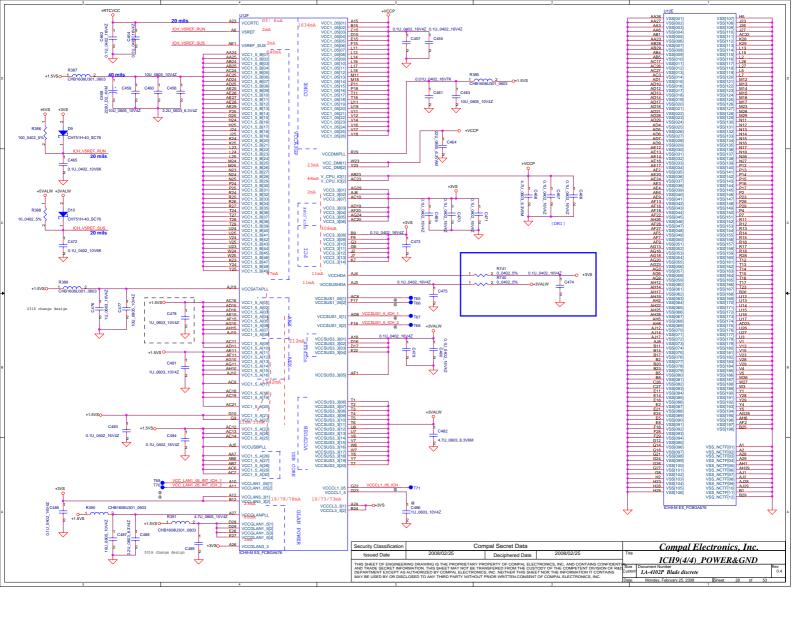


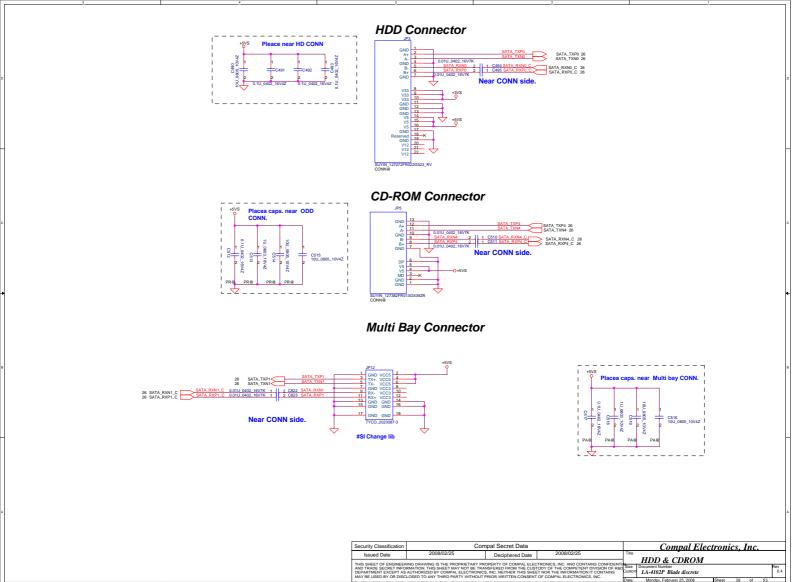
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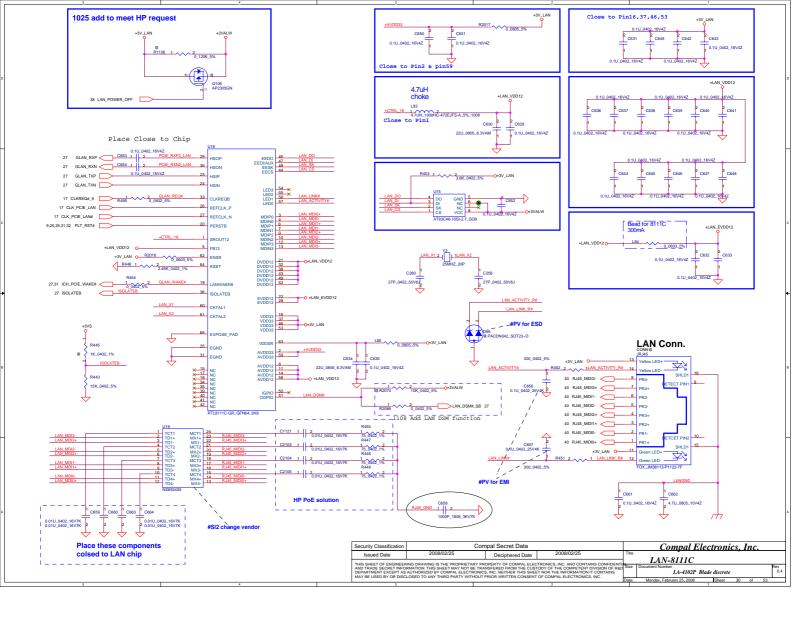
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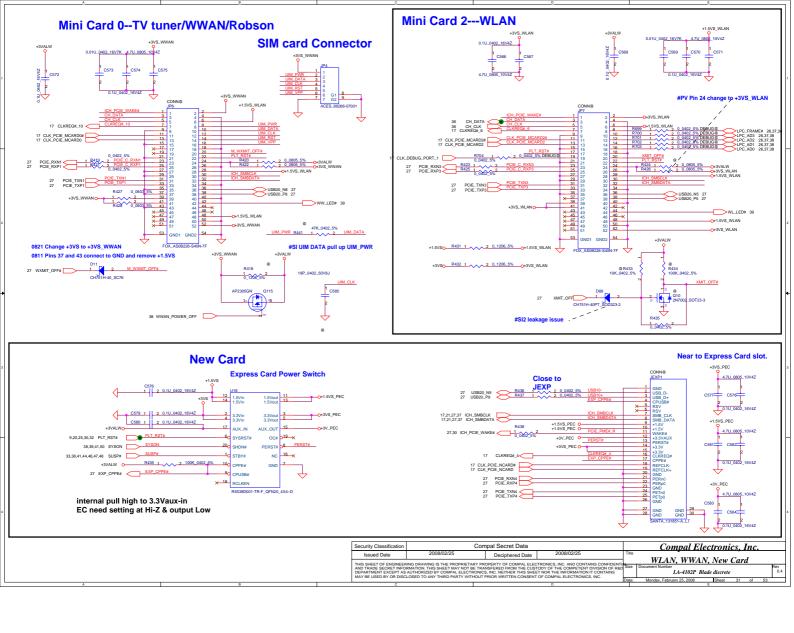


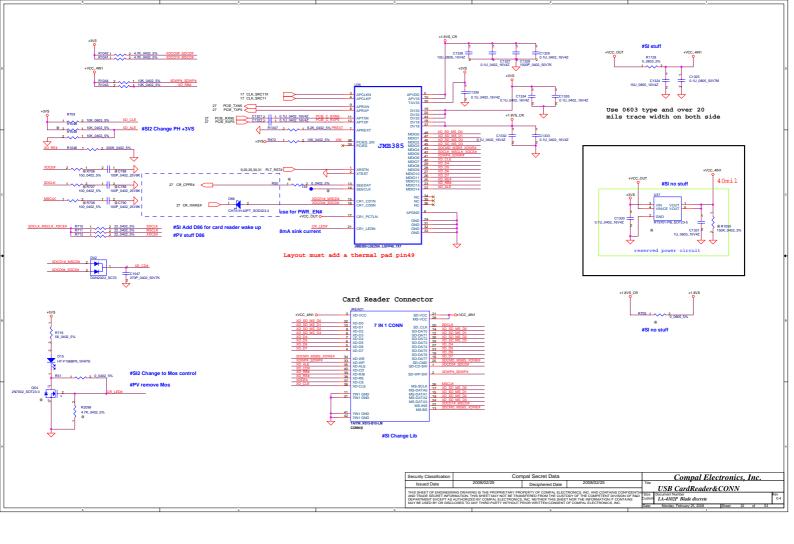


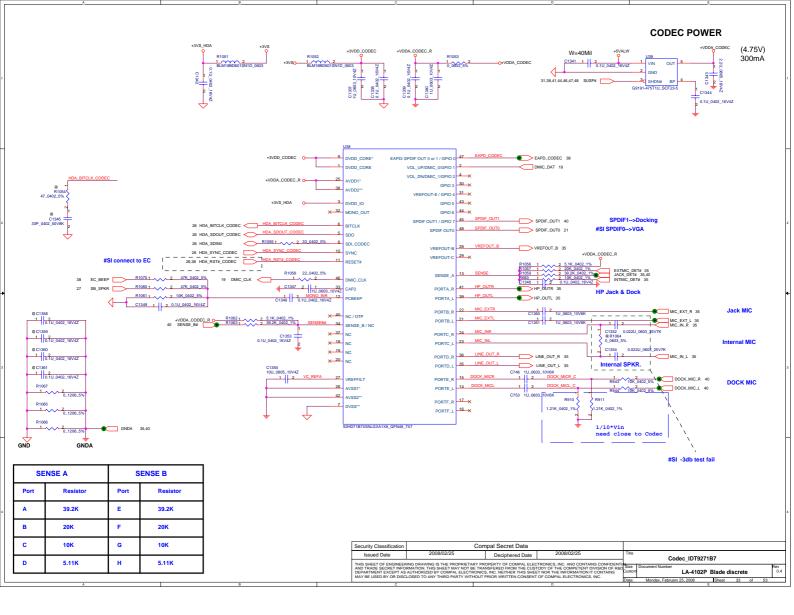


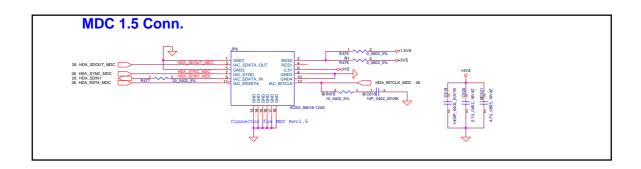




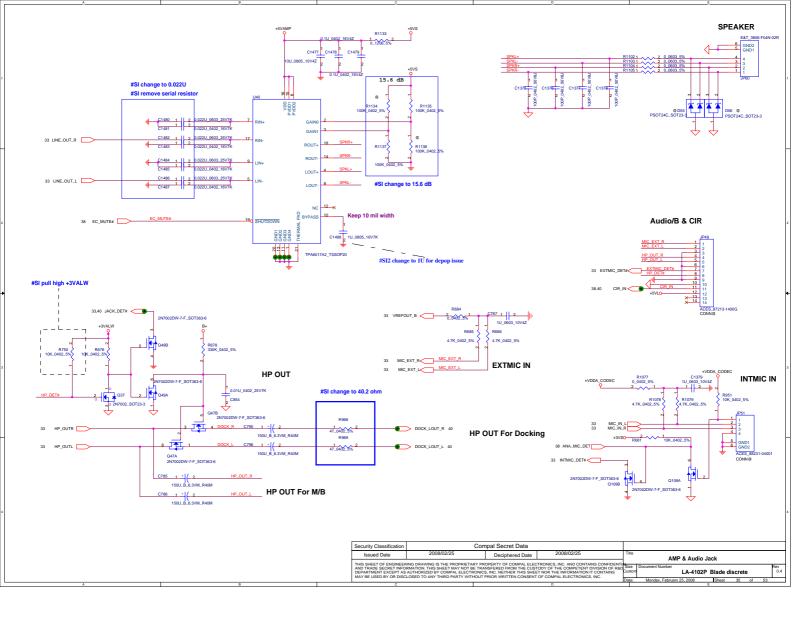


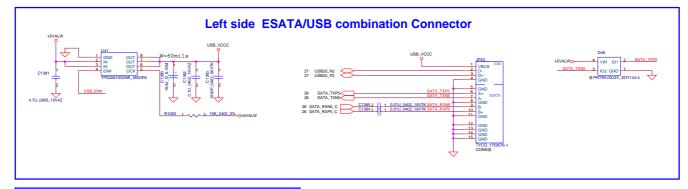


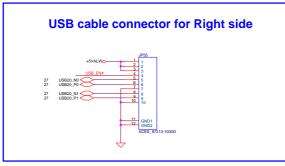


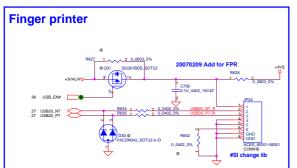


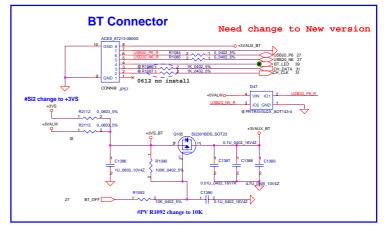
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				Date:	Monday, February 25, 2008 Sheet 34 of	53

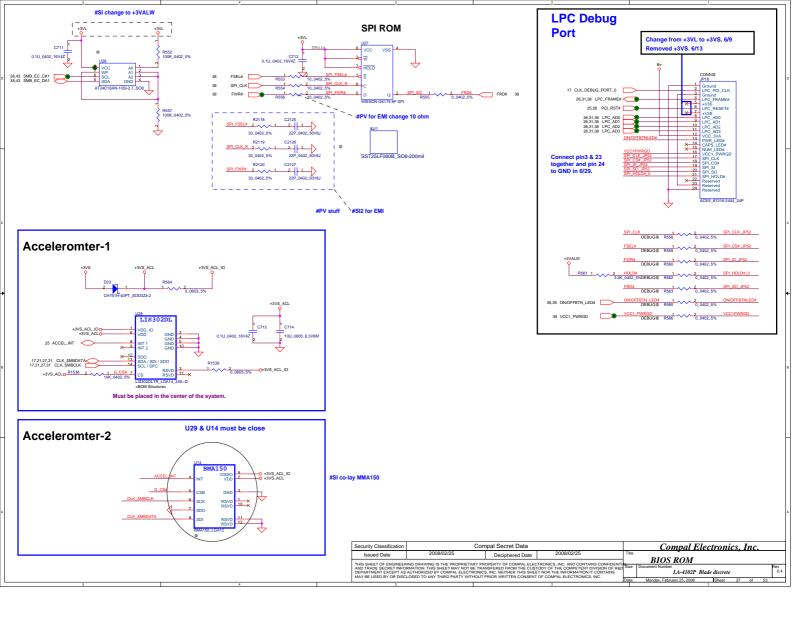


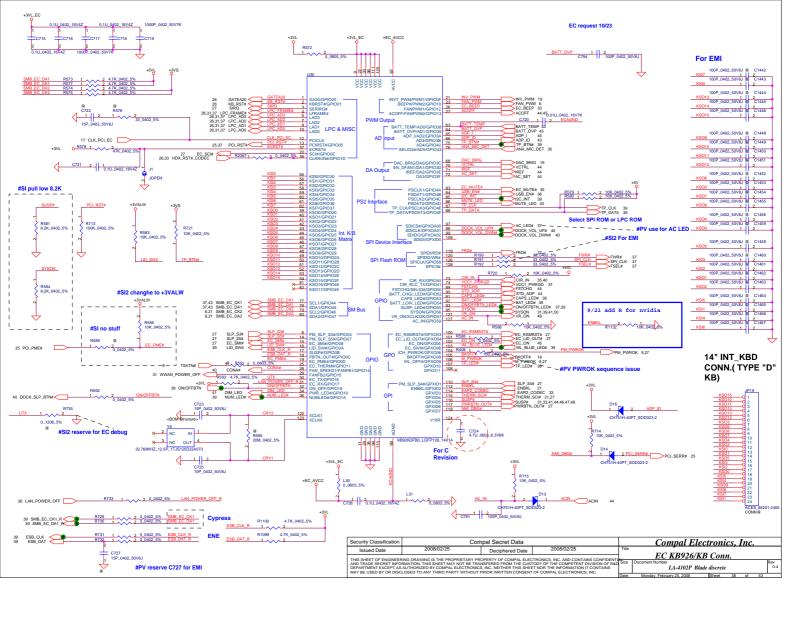


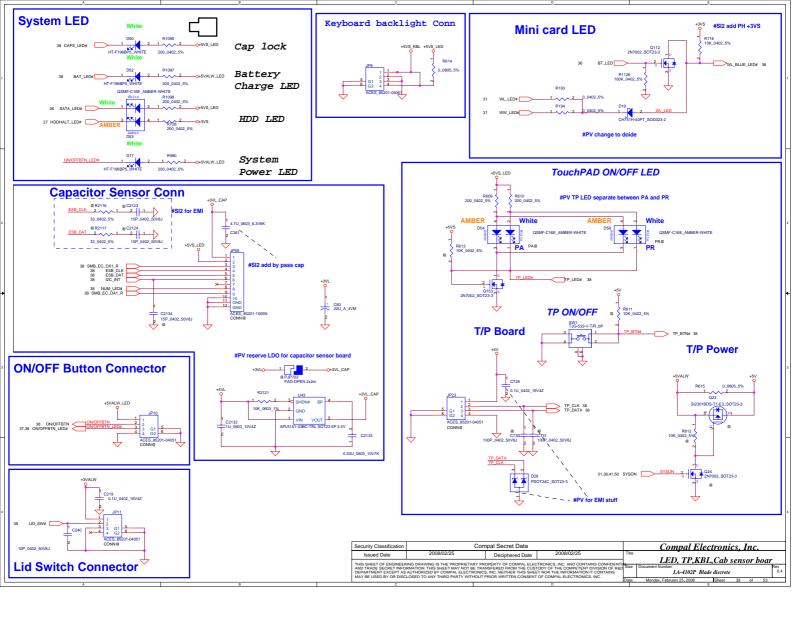


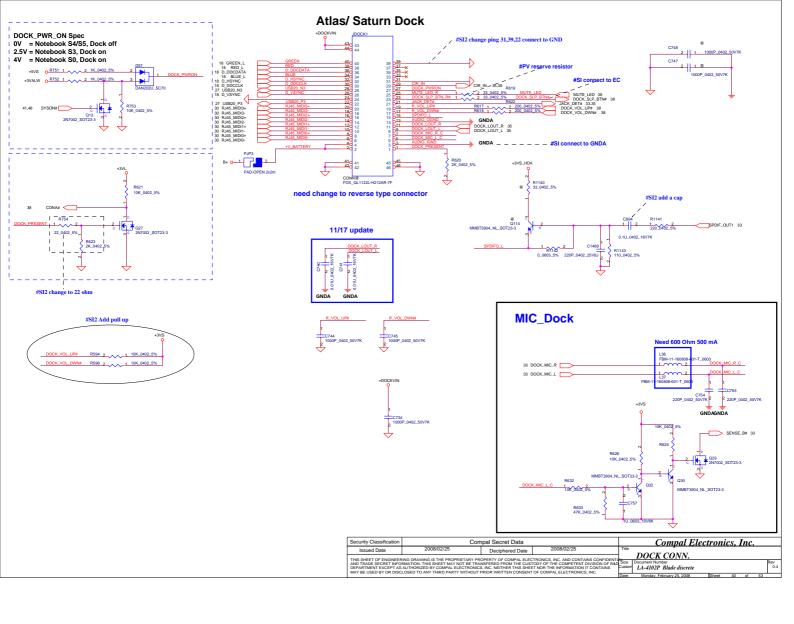


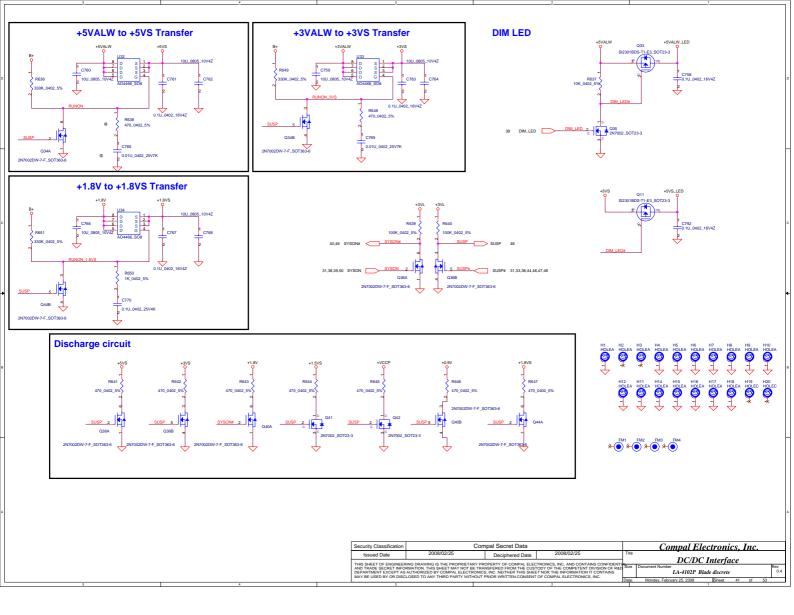


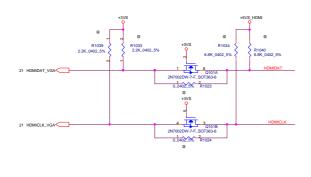


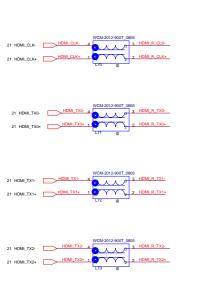


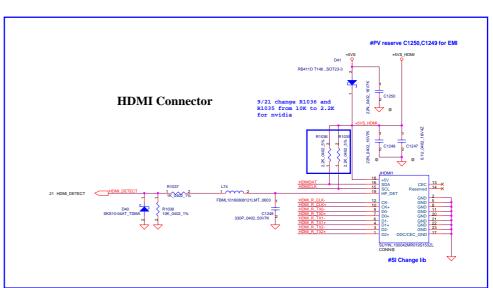




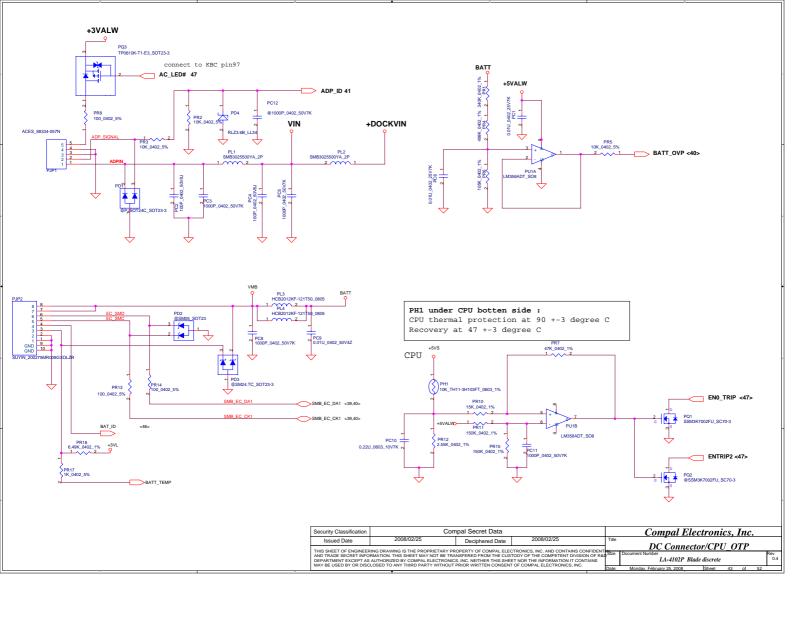


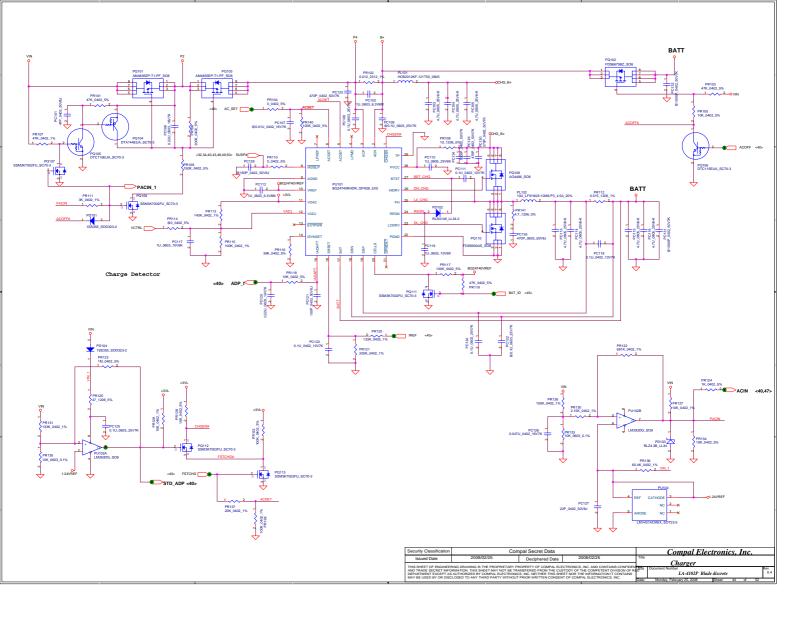


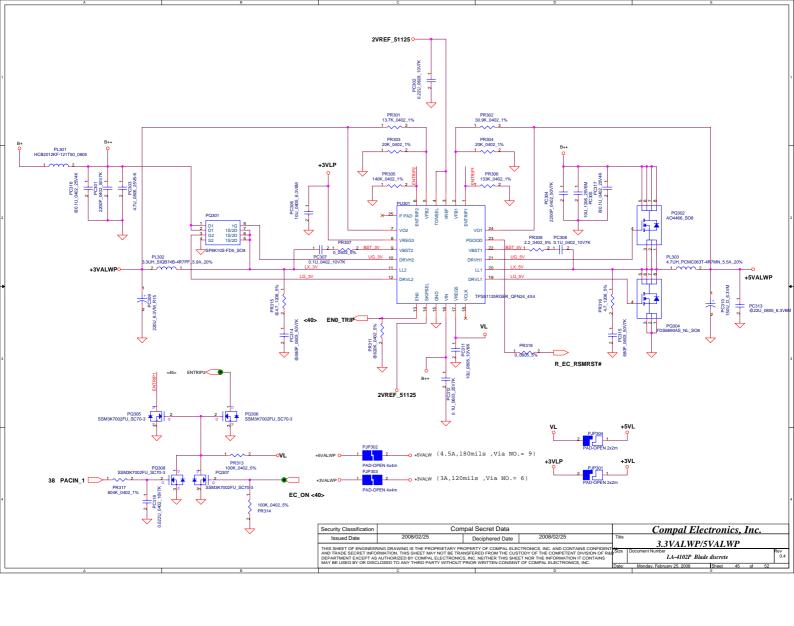


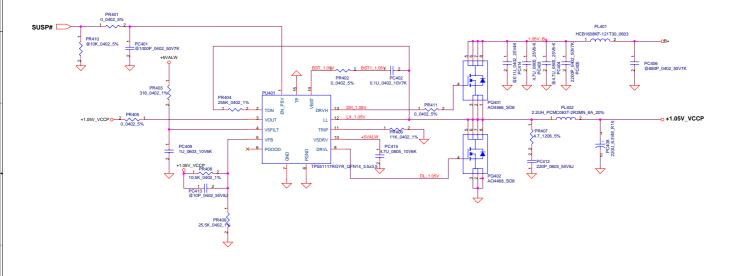


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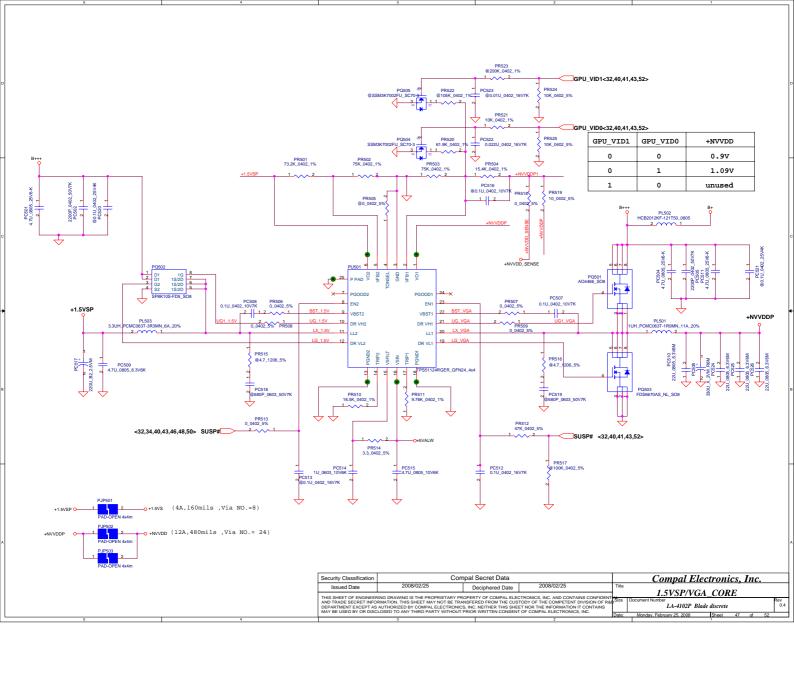


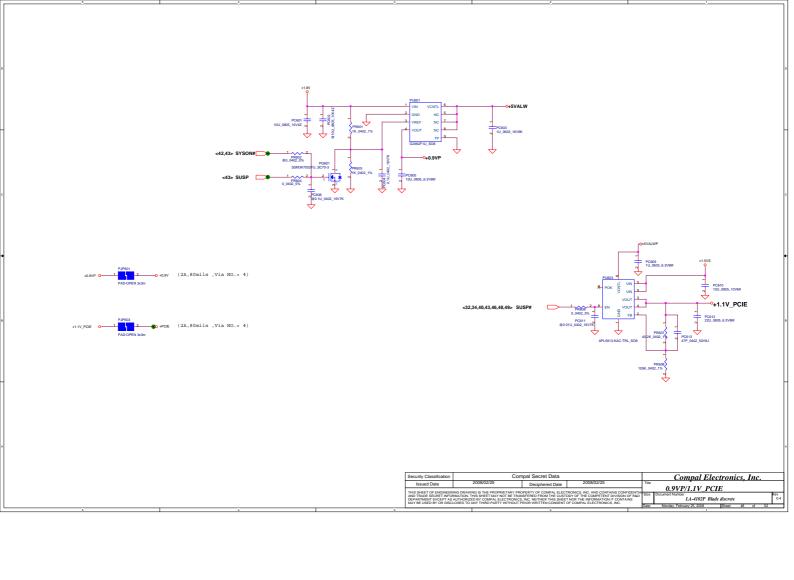


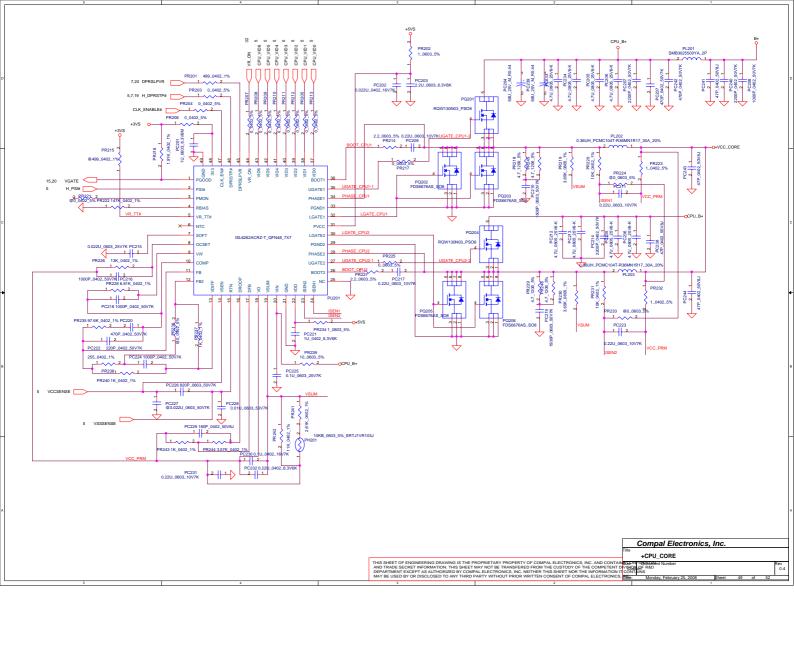


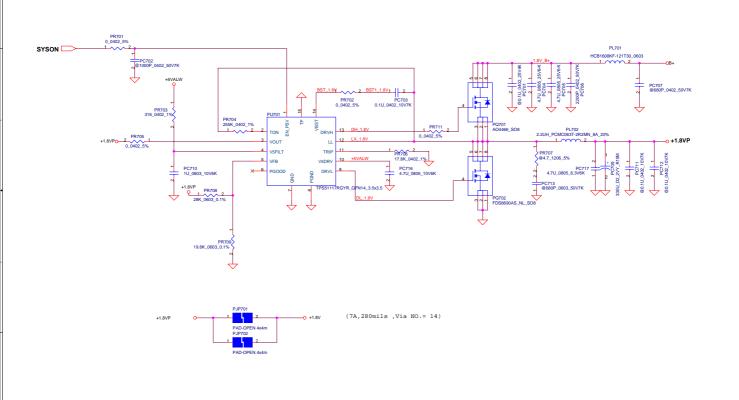
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Compal Electronics, Inc.

LA-4102P Blade discrete

1.8VP

Ve	Version Change List (P. I. R. List) for Power Circuit										
Item	Page#	Title	Date	Request Owner	Issue Description		Solution Description	Rev.			
, 1	43	DC Connector /CPU_OTP	11/06	Compal	Add PD4 & PC12		Add PD4 & PC12				
2	45	3.3VALWP/5VALWP	11/06	Compal	for Layout		Change PQ301, cancel PQ303.				
3	44	Charger	11/06	Compal	EMI solution		Add PC128				
4	49	CPU_CORE	11/06	Compal	EMI solution		Add PC240				
5	47	1.5VSP/VGA_CORE	11/06	Compal	for VGA voltage steps		Add PQ505, PR523, PR524, PR525				
6	45	3.3VALWP/5VALWP	12/31	Compal	PWR request		Add PU302, control signal changed to ACOFF	2			
7	44	Charger	12/31	Compal	EMI solution		Add PC129, PC130, PC131, PC132, PC133				
8	49	+CPU_CORE	12/31	Compal	EMI solution		Add PC242				
9	47 +	1.5VSP/VGA COREP	01/02	Compal	HW request		Change PR513 to 0_ohm				
10	44	Charger	01/02	Compal	EMI solution		Add PC135 and PR141				
11	49	+CPU_CORE	02/15	Compal	Change high-side MOS for WWAP	N	Change PQ201 and PQ204 to powerpak				
12	43	DC Connector /CPU_OTP	02/15	Compal	AC LED change to KBC control		ACLED# connect to EC pin 97	3			
13	43	DC Connector /CPU_OTP	02/19	Compal	WWAM issue		add PC241 47pF				
14	49	+CPU_CORE	02/19	Compal	WWAM issue		add PC243 PC244 47pF				
4								4			
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A   Delete LVDS 8 channel   19.20   Schematic Delete   19.20   Schematic	$\overline{}$	<del></del>
2   Disable TV out function from Docking   20   TV signal unconnected, DACS_VDD pull low 10K (R946).	Date	Phase
1	11/21   _	DB
Supplement Contenting Uniform   Supplement Content Uniform   Supplement Co	11/07	DB
Source   S	-  -   11/17   -  -	DB
Reserve Card reader DSE function	11/17	DB
7   Swap PCIE LAN and New card   27   Swap PCIE 4 and PICE6	11/07	DB
8   Change GPU 1.8VS power   20, 21   Change 1.8VS to +VDD_MEM18     9   Change G sensor control from SB, LED drive by +5VS   27, 39   Change G sensor control from SB     10   Avoid Sattery mode can't boot issue   38, 45   Add +3VALW GD to EC_RSMRST# to fix Battery mode can't boot issue     11   Add G sensor ST and Bosch   37   Add G sensor ST and Bosch   37   Add G sensor ST and Bosch   37   Add G sensor ST and Bosch   38   48   Add +3VALW GD to EC_RSMRST# to fix Battery mode can't boot issue     12   Change LAN solution (Marvell to Realtek)   30   Change LAN solution (Marvell to Realtek)   30   Change LAN solution (Marvell to Realtek)   30   U19 Change to correct transformer type   31   LAN transformer interfere   30   U19 Change to correct transformer type   32   Lack can't detect normal   33   R1089 change from 39.2 to 39.2K   R1128->Sluff, R705->@, Cardreader LED->+5VS, add D3E function   32   R708->10K, R1047->B.2K, R1128->Sluff, R705->@, U37->-@, Cardreader LED->+5VS, add D3E function   33   R1089 change from 39.2 to 39.2K   39.2	11/17	DB
9 Change G sensor control from SB, LED drive by +5VS 27, 39 Change G sensor control from SB 10 Avoid Battery mode can't boot issue 38, 45 Add +3VALW GD to EC_RSMRST# to fix Battery mode can't boot issue 11 Add G sensor ST and Bosch 37 Add G sensor ST and Bosch 12 Change LAN solution (Marvell to Realtek) 30 Change LAN solution (Marvell to Realtek) 13 LAN transformer interfere 30 U19 Change to correct transformer type 14 Cardreader schematic review add D3E function 32 R709→10K, R104T→9.2.K, R1128→Stuff, R705→@, U37→@, Cardreader LED→+5VS, add D3E function 15 Jack can't detect normal 33 R1059 change from 39.2 to 39.2 k 16 Docking can not power on 40 Add power on circuit D57,013R751,R752,R753 17 HP audio team recommend 33, C1480−C1487, C1352, C1354 change to 0.022U, Amp output setup to 15.6 dB, Reserve C747, C748 for GNDA and GND 18 Audio jack can't detect normal 35 Add Pull up resistor R750 to +3VALW 19 Docking HP audio test fail 35 Add C795, C796 to avoid DC level, and add R968, R969 to reduce HP out level 20 Leakage problem 38 Correct direction pretect leakage 21 EC pin define update 38 Correct direction pretect leakage 22 Can't Hebenation(SLP_S4#) 38 Correct Greetion pretect leakage 23 EC can't receive docking present 40 CONA# change +3VL 24 Reserve capacitor on digital MIC for EMI request 19 Add C496,C498 25 Add 2N7002 to GND on HDMI to avoid leakage. 21 Add G74 26 +VDD_MEM18 to +1.8VS, change to jummper 22 Delete R1124,R1125 add PUP605 27 HDCP R0M fail. HDCP_SCL need pull high. 22 R224 no stuff. R213 stuff. 28 Reserve capacitor on digital MIC for SED. WWAN noise 26 Add C498,C502	11/17	DB
10   Avoid Battery mode can't bool issue   38, 45   Add 43VALW GD to EC_RSMRST# to fix Battery mode can't bool issue   11   Add G sensor ST and Bosch   37   Add G sensor ST and Bosch   37   Add G sensor ST and Bosch   38   Add G sensor ST and Bosch   38   Change LAN solution (Marvell to Realtek)   30   Change LAN solution (Marvell to Realtek)   30   Change LAN solution (Marvell to Realtek)   31   LAN transformer interfere   30   U19 Change to correct transformer type   32   LAN transformer interfere   33   U19 Change to correct transformer type   33   LAN transformer interfere   30   U19 Change to correct transformer type   34   LAN transformer interfere   30   U19 Change to correct transformer type   37   LAN transformer interfere   30   U19 Change to correct transformer type   38   LAN transformer interfere   30   U19 Change to correct transformer type   39   Lask can't detect normal   33   R1059 change from 39.2 to 39.2 kt   40   Add power on circuit D57,0138751,R752,R753   Add power on circuit D57,0138751,R752,R753   Add Pall up resistor R750 to +3VALW   Add power on circuit D57,0138751,R752,R753   Add Pall up resistor R750 to +3VALW   Add power on circuit D57,0138751,R752,R753   Add C795, C796 to avoid DC level, and add R968, R969 to reduce HP out level   20   Leakage problem   38   Correct direction pretect leakage   Daleite EC PARE, S750N PU, SUSP# FU, LID, SW# change to +3VALW, Delete CLKRUN#, R562>@ for C6 chip, CiR PU+SVL, add 100P to BATT_OVP(EC recommend)   Connect SLP_S44 to SB   Cannt receive docking present   40   CONA# change +3VL   Add C496,C498   Add C496,C498   Add C496,C498   Reserve capacitor on digital MIC for EMI request   19   Add C496,C498   Reserve capacitor on digital MIC for SED. WWAN noise   26   Add C498,C502   Connect State   Compat Secret Data   Compa	11/17	DB
11   Add G sensor ST and Bosch   37   Add G sensor ST and Bosch   37   Add G sensor ST and Bosch   38   Add G sensor ST and Bosch   39   Change LAN solution (Marvell to Realtek)   30   Change LAN solution (Marvell to Realtek)   30   Change LAN solution (Marvell to Realtek)   30   U19 Change to correct transformer type   14   Cardreader schematic review,add D3E function   32   R709→310K, R1047→8.2K, R1128→Stuff, R705→@, U377→@, Cardreader LED→3+5VS, add D3E function   15   Jack can't detect normal   33   R1059 change from 39.2 to 39.2K   16   Docking can not power on   40   Add power on circuit D57,013R751,R752,R753   17   HP audio team recommend   33, 35   C1480−C1487, C1352, C1354 change to 0.022U, Amp output setup to 15.6 dB, Reserve C747, C748 for GNDA and GND   18   Audio jack can't detect normal   35   Add Pull up resistor R750 to +3VALW   19   Docking HP audio test fail   35   Add C795, C796 to avoid DC level, and add R968, R969 to reduce HP out level   20   Leakage problem   38   Correct direction pretect leakage   Delefe EC PMEE, SYSON PU, SUSP# FU, LID SW# change to +3VALW, Delete CLKRUNR, R562→@ for C0 chip, CIR   PULVIL, add 1000 to BATT_OVP[EC recommend)   CORNA# change +3VL   Add C745   Add C746, C498   Add C740, C496, C498   C496, C496, C498   C496,	11/17	DB
12   Change LAN solution (Marvell to Realtek)   30   Change LAN solution (Marvell to Realtek)   30   U19 Change to correct transformer type   31   LAN transformer interfere   30   U19 Change to correct transformer type   32   R709->10K, R1047->8.2K, R1128->5tuff, R705->69, U37->69, Cardreader LED->+5VS, add D3E function   32   R709->10K, R1047->8.2K, R1128->5tuff, R705->69, U37->69, Cardreader LED->+5VS, add D3E function   33   R1059 change from 39.2 to 39.2K   33   R1059 change from 39.2 to 39.2K   34   Add power on circuit D57,0138751,R752,R753   35   C1480-C1487, C1352, C1354 change to 0.022U, Amp output setup to 15.6 dB, Reserve C747, C748 for GNDA and GND   35   Add Opidity resistor R750 to +3VALW   35   Add C795, C796 to avoid DC level, and add R968, R969 to reduce HP out level   36   Correct direction pretect leakage   Dalete EC_PMEE, SYSON PU, SUSP# PU, LID_SW# change to *3VALW, Delete CLKRUN#, R582-36 for C0 chip., CIR   Delete Card receive docking present   40   CONA# change +3VL   24   Reserve capacitor on digital MIC for EMI request   19   Add C495,C498   25   Add 2N7002 to GND on HDMI to avoid leakage.   21   Add Q74   Reserve capacitor on digital MIC for EMI request   22   Delete R1124,R1125 add PJP605   23   R224 no stuff, R213 stuff.   24   Reserve capacitor on digital MIC for SED, WWAN noise   26   Add C499,C502   Securey Classification   Compati Securey Delate   Compati Secure Data   Com	11/17	DB
13	11/17	DB
14 Cardreader schematic review, add D3E function 32 R709~>10K, R1047~>8.2K, R1128~Stuff, R705~>®, U37~>®, Cardreader LED~>+5VS, add D3E function 15 Jack can't detect normal 33 R1059 change from 39.2 to 39.2K  16 Docking can not power on 40 Add power on circuit D57,Q13R751,R752,R753  17 HP audio team recommend 33, 35 C1480~C1487, C1352, C1354 change to 0.022U, Amp output setup to 15.6 dB, Reserve C747, C748 for GNDA and GND 18 Audio jack can't detect normal 35 Add C795, C796 to avoid DC level, and add R968, R969 to reduce HP out level 20 Leakage problem 35 Correct direction pretect leaked problem 36 Correct direction pretect leaked problem 27 Delete EC, PME, SYSON PU, SUSP PU, LID, SW# change to +3VALW, Delete CLKRUNE, R582>® for C0 chip, Cirk PU+SVL, add 100P to BATT_OVP(EC recommend) 28 IEC can't receive docking present 40 CONA¢ change +3VL 24 Reserve capacitor on digital MIC for EMI request 19 Add C496,C498 26 I+VDD_MEM18 to +1.8VS, change to jummper 22 Delete R1124,R1125 add PJP605 27 HDCP ROM fail. HDCP_SCL need pull high, 22 R224 no stuff. R213 stuff. 28 Reserve capacitor on digital MIC for SED. WWAN noise 26 Add C499,C502	-  -   11/17   _	DB
15   Jack can't detect normal   33   R1059 change from 39.2 to 39.2 K	11/17	DB
16 Docking can not power on 40 Add power on circuit D57,Q13R751,R752,R753  17 HP audio team recommend 33, 35 C1480-C1487, C1352, C1352, C1352, C1352, Change to 0.022U, Amp output setup to 15.6 dB, Reserve C747, C748 for GNDA and GND  18 Audio jack can't detect normal 35 Add Pull up resistor R750 to +3VALW  19 Docking HP audio test fail 35 Add C795, C796 to avoid DC level, and add R968, R969 to reduce HP out level  20 Leakage problem 38 Correct direction pretect leakage  21 EC pin define update 38 Delete EC PME#, SYSON PU, SUSP# PU, LID_SW# change to +3VALW, Delete CLKRUN#, R582->@ for C0 chip, CIR PU+SVL, add 100P to BATT_OVP(EC recommend)  22 Can't Hibernation(SLP_S4#) 38 Connect SLP_S4# to SB  23 EC can't receive docking present 40 CONA# change +3VL  24 Reserve capacitor on digital MIC for EMI request 19 Add C496,C498  25 Add 2N7002 to GND on HDMI to avoid leakage. 21 Add Q74  26 +VDD_MEM18 to +1.8VS, change to jummper 22 Delete R1124,R1125 add PJP605  27 HDCP ROM fail. HDCP_SCL need pull high. 22 R224 no stuff. R213 stuff.  28 Reserve capacitor on digital MIC for SED. WWAN noise 26 Add C499,C502	11/17	DB
17 HP audio team recommend  18 Audio jack can't detect normal  19 Docking HP audio test fail  20 Leakage problem  21 EC pin define update  22 Can't Hibernation(SLP_S4#)  38 Connect SLP_S4# to SB  23 EC can't receive docking present  40 CONA# change +3VL  24 Reserve capacitor on digital MIC for EMI request  25 Add C748. C1487, C1352, C1354 change to 0.022U, Amp output setup to 15.6 dB, Reserve C747, C748 for GNDA and GND  38 Correct direction pretect leakage  Delete EC_PME#, SYSON PU, SUSP# PU, LID_SW# change to +3VALW, Delete CLKRUN#, R582>@ for C0 chip, CiR PU+SVL, add 100P to BATT_OVP(EC recommend)  CONA# change +3VL  24 Reserve capacitor on digital MIC for EMI request  19 Add C496,C498  25 Add 2N7002 to GND on HDMI to avoid leakage.  21 Add Q74  22 Delete R1124,R1125 add PJP605  27 HDCP ROM fail, HDCP_SCL need pull high.  28 Reserve capacitor on digital MIC for SED. WWAN noise  28 Reserve capacitor on digital MIC for SED. WWAN noise  29 Add C499,C502	-  -   11/17   _   -	DB
Add Pull up resistor R750 to +3VALW  19 Docking HP audio test fail 35 Add C795, C796 to avoid DC level, and add R968, R969 to reduce HP out level  20 Leakage problem 38 Correct direction pretect leakage 21 EC pin define update 38 Pul+SVL, add 1009 to BATT_OVP(EC recommend)  22 Can't Hibernation(SLP_S4#) 38 Connect SLP_S4# to SB  23 EC can't receive docking present 40 CONA# change +3VL  24 Reserve capacitor on digital MIC for EMI request 19 Add C496,C498  25 Add 2N7002 to GND on HDMI to avoid leakage. 21 Add Q74  26 +VDD_MEM18 to +1.8VS, change to jummper 22 Delete R1124,R1125 add PJP605  27 HDCP ROM fail. HDCP_SCL need pull high. 28 Reserve capacitor on digital MIC for SED. WWAN noise 26 Add C499,C502  Security Classification Compal Secret Data Compal Secret Data  Compal Elecc	11/17	DB
19 Docking HP audio test fail 35 Add C795, C796 to avoid DC level, and add R968, R969 to reduce HP out level 20 Leakage problem 38 Correct direction pretect leakage 21 EC pin define update 38 Delete EC_PME#, SYSON PU, SUSP# PU, LID_SW# change to +3VALW, Delete CLKRUN#, R582->@ for C0 chip, CIR PU+5VL, add 100P to BATT_OVP(EC recommend) 22 Can't Hibernation(SLP_S4#) 38 Connect SLP_S4# to SB 23 EC can't receive docking present 40 CONA# change +3VL 24 Reserve capacitor on digital MIC for EMI request 19 Add C496,C498 25 Add 2N7002 to GND on HDMI to avoid leakage. 21 Add Q74 26 +VDD_MEM18 to +1.8VS, change to jummper 22 Delete R1124,R1125 add PJP605 27 HDCP ROM fail. HDCP_SCL need pull high. 22 R224 no stuff. R213 stuff. 28 Reserve capacitor on digital MIC for SED. WWAN noise 6 Add C499,C502		DB
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Delete EC_PME#, SYSON PU, SUSP# PU, LID_SW# change to +3VALW, Delete CLKRUN#, R582->@ for C0 chip, CIR PU+5VL, add 100P to BATT_OVP(EC recommend)	11/17	DB
21   EC pin define update   38   PU+5VL, add 100P to BATT_OVP(EC recommend)	11/07	DB
23   EC can't receive docking present	_      11/07	DB
24 Reserve capacitor on digital MIC for EMI request  19 Add C496,C498  25 Add 2N7002 to GND on HDMI to avoid leakage.  21 Add Q74  26 I +VDD_MEM18 to +1.8VS, change to jummper  22 Delete R1124,R1125 add PJP605  27 HDCP ROM fail. HDCP_SCL need pull high.  28 Reserve capacitor on digital MIC for SED. WWAN noise  26 Add C499,C502  Security Classification  Compal Secret Data  Compal Elect	11/17	DB
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25   Add 2N7002 to GND on HDMI to avoid leakage.   21   Add Q74     26   +VDD_MEM18 to +1.8VS, change to jummper   22   Delete R1124,R1125 add PJP605     27   HDCP ROM fail. HDCP_SCL need pull high.   22   R224 no stuff. R213 stuff.     28   Reserve capacitor on digital MIC for SED. WWAN noise   26   Add C499,C502     Security Classification   Compal Secret Data   Compal Elect	11/07	DB
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Item	Fixed Issue (Reason for change)	PAGE	Modify List	Date	Phase	Ī		
1	Change transformer vendor	30	change U19 library	01/04	SI			
2	XMIT_OFF add a diode to avoid leakage.	31	Add D88	01/04	SI	1		
3	Card reader recommend	32	XD_ALE need pull +3VS not pull low.	01/04	SI	1		
4	change Q54 from transistor to MOS for cardreader LED.	32	Change Q54	01/04	SI	1		
5	speaker pop issue	35	Change C1488 to 1U	01/04	SI	1		
6	Reserve capacitor on SPI_FSEL#,CLK#,FER for EMI request	36	Add C2125,C2126,C2127	01/04	SI	1		
7	Change EC_PME pull high from +3VL to +3VALW	38	R585 stuff	01/04	SI	1		
8	Reserve damping resistor on SPI_CLK for EMI request	38	Add R191	01/04	SI	1		
9	WLAN LED issue,WL_BLUE_LED# pull +3VS	39	Add R716	01/04	SI	1		
10	Add bypass capacitance on sensor bottom	39	Add C261(4.7U)	01/04	SI	1		
11	EC can't detect DOCK_PRESENT.	40	change R754 to 22 Ohm,R623 to 2K	01/04	SI	1		
12	Add DOCK_VOL_UP#,DOCK_VOL_Down# pull +3VS	40	Add R594,R596	01/04	SI	1		
13	SPDIF issue	40	follow Vader	01/04	SI	1		
14	Docking CRT blurred	40	Change ping 31,39,22 connect to GND	01/04	SI			
15	Change R650 and C770 to modify the power sequence	41	change R650 to 1K, C770 to 0.1u	01/04	I SI	1.		
16	Add 12P on CLK_14M_ICH for WWAN noise	17	Add 12P on CLK_14M_ICH	02/15	PV			
17	BKOFF# reserve pull low 10K	19	reserve R717	02/15	PV	1		
18	Reserve CMD27 to support 64M X16	7,8	Reserve CMD27 to support 64M X16	02/15	PV	1		
19	Reserve cap on HDA_BITCLK for WWAN noise issue	26	Reserve cap on HDA_BITCLK	02/15	PV	1		
20	Reserve to prevent ESD issue	30	Reserve ESD diode on LAN LED pin	02/15	PV	1		
21	Change WLAN and WWAN 0402 resistor to 0805	31	Change WLAN and WWAN 0402 resistor to 0805, and WLAN change to +3VS power plane	02/15	PV	1		
22	Direct drive LED, and add D3E function diode	32	Direct drive LED and XD_ALE Pull L, and add D86 for D3E function	02/15	PV	1		
23	Change R1092 value on BT power switch Gate	36	Change R1092 to 10K	02/15	PV	1		
24	Correct AC_LED control by EC	38	AC_LED Change controll by EC	02/15	PV	1		
25	Change all LED limit current resistor to 200 ohm	39	Change all LED limit current resistor to 200 ohm and add Touch pad LED for PR					
26	Add 33 ohm for MUTE_LED and DOCK_SLP_BTN#	40	Add 33 ohm for MUTE_LED and DOCK_SLP_BTN#					
27	follow check list ver:1.5	6	change R13 to 56 ohm;change R2~R8 to 51 ohm;change R11 to 0ohm					
28	Reserve Cap for EMI	42	add C1250,C1249	02/20	PV	1		
			Security Classification Compal Secret Data Compal Electric Issued Date 2008/02/25 Deciphered Date 2008/02/25 Title HW PIR THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC., AND CONTAINS CONFIDENTIAL TOWNS OF THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC., AND CONTAINS CONFIDENTIAL TOWNS OF THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC., AND CONTAINS CONFIDENTIAL TOWNS OF THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC., AND CONTAINS CONFIDENTIAL TOWNS OF THE PROPRIETARY PROPERTY OF COMPACT ELECTRONICS, INC., AND CONTAINS CONFIDENTIAL TOWNS OF THE PROPRIETARY PROPERTY OF COMPACT ELECTRONICS, INC., AND CONTAINS CONFIDENTIAL TOWNS OF THE PROPRIETARY PROPERTY OF COMPACT ELECTRONICS, INC., AND CONTAINS CONFIDENTIAL TOWNS OF THE PROPRIETARY PROPERTY OF COMPACT ELECTRONICS, INC., AND CONTAINS CONFIDENTIAL TOWNS OF THE PROPRIETARY PROPERTY OF COMPACT ELECTRONICS, INC., AND CONTAINS CONFIDENTIAL TOWNS OF THE PROPRIETARY PROPERTY OF COMPACT ELECTRONICS, INC., AND CONTAINS CONFIDENTIAL TOWNS OF THE PROPRIETARY PROPERTY OF COMPACT ELECTRONICS, INC., AND CONTAINS CONFIDENTIAL TOWNS OF THE PROPRIETARY PROPERTY OF COMPACT ELECTRONICS, INC., AND CONTAINS CONFIDENTIAL TOWNS OF THE PROPRIETARY PROPERTY OF COMPACT ELECTRONICS, INC., AND CONTAINS CONFIDENTIAL TOWNS OF THE PROPRIETARY PROPERTY OF COMPACT ELECTRONICS, INC., AND CONTAINS CONFIDENTIAL TOWNS OF THE PROPERTY OF COMPACT ELECTRONICS, INC., AND CONTAINS CONFIDENTIAL TOWNS OF THE PROPERTY OF COMPACT ELECTRONICS, INC., AND CONTAINS CONFIDENTIAL TOWNS OF THE PROPERTY OF COMPACT ELECTRONICS, INC., AND CONTAINS CONFIDENTIAL TOWNS OF THE PROPERTY OF COMPACT ELECTRONICS, INC., AND CONTAINS CONFIDENTIAL TOWNS OF THE PROPERTY OF COMPACT ELECTRONICS, INC., AND CONTAINS CONFIDENTIAL TOWNS OF THE PROPERTY OF COMPACT ELECTRONICS, INC., AND CONTAINS CONFIDENTIAL TOWNS OF THE PROPERTY OF THE PROPERTY OF COMPACT ELECTRONICS, INC., AND CONTAINS CONFIDENTIAL TOWNS OF THE PROPERTY OF THE PROPERTY OF THE PROPERTY OF THE PROPERTY OF THE P	tronics,	Inc.	_		

LA-4102P Blade discrete

Item	Fixed Issue (Reason for change)	PAGE	Modify List	Date	Phase
1	follow check list Ver:1.5	17	reserve R148	02/15	PV
2	follow check list Ver:1.5	0	change R45,R48 to 10K	02/15	PV
3	boot code "88" power sequence faill	27	add Diode from PWROK to RSMRST	02/15	PV
4	Change BT,LAN,DOCK,Multibay connect for DFX	   		02/15	PV
5	Change WWAN and WLAN LED	39		02/15	PV
6	For EMI		SPI_CLK add R2118 , R2119 , R2120 => 330hm add C2125 , C2126 , C2127 => 22pF;R553, 554, 556 =>100hm	02/15	PV
7	For EMI	30	LAN add C656 and C657 => 0.1uF	02/15	PV
8	For EMI	39	T/P add D28 and C729	02/15	PV
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